

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/08/2022

Details for "TLC082QDGNRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLC082QDGNRQ1	NIPDAU	Level-3-260C-168 HR	Ext-Mfg	DGN 8	3x3x1	26.9

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000003	0.004885	49	0.000011	0
Precious Metals	Gold	7440-57-5	0.061414	99.995115	999951	0.228247	2282
Sub-Total			0.061417	100	1000000	0.228258	2283
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.251401	72.999985	730000	0.93434	9343
Thermoplastics	Epoxy	85954-11-6	0.092984	27.000015	270000	0.345578	3456
Sub-Total			0.344385	100	1000000	1.279918	12799
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	10.86848	97.04	970400	40.393057	403931
Copper and Its Alloys	Iron	7439-89-6	0.2912	2.6	26000	1.082254	10823
Copper and Its Alloys	Phosphorus	7723-14-0	0.0168	0.15	1500	0.062438	624
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00112	0.01	100	0.004163	42
Zinc and Its Alloys	Zinc	7440-66-6	0.0224	0.2	2000	0.08325	833
Sub-Total			11.2	100	1000000	41.625162	416252
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.192142	95.119802	951198	0.714102	7141
Precious Metals	Gold	7440-57-5	0.001576	0.780198	7802	0.005857	59
Precious Metals	Palladium	7440-05-3	0.008282	4.1	41000	0.03078	308
Sub-Total			0.202	100	1000000	0.75074	7507
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	11.732174	84.999998	850000	43.603004	436030
Other Plastics and Rubber	Carbon Black	1333-86-4	0.041408	0.300002	3000	0.153894	1539
Thermoplastics	Epoxy	85954-11-6	2.028976	14.7	147000	7.540755	75408
Sub-Total			13.802558	100	1000000	51.297653	512977
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.296442	100	1000000	4.818269	48183
Sub-Total			1.296442	100	1000000	4.818269	48183
Total			26.906802			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.